APPARATUS FOR ELIMINATING WAFER WARPAGE

Abstract of the Disclosure

Provided is an apparatus for eliminating wafer warpage including: a wafer support member which contacts the rim of the bottom surface of a wafer that is to be marked and supports the wafer; a press member which is disposed on the wafer support member and is installed to be able to move between a descended position in which the press member presses the wafer onto the wafer support member by pressing the rim of the upper surface of the wafer supported by the wafer support member and an ascended position in which the press member is upwardly apart from the wafer; and a driving means which raises the press member to the ascended position.

Figure 2